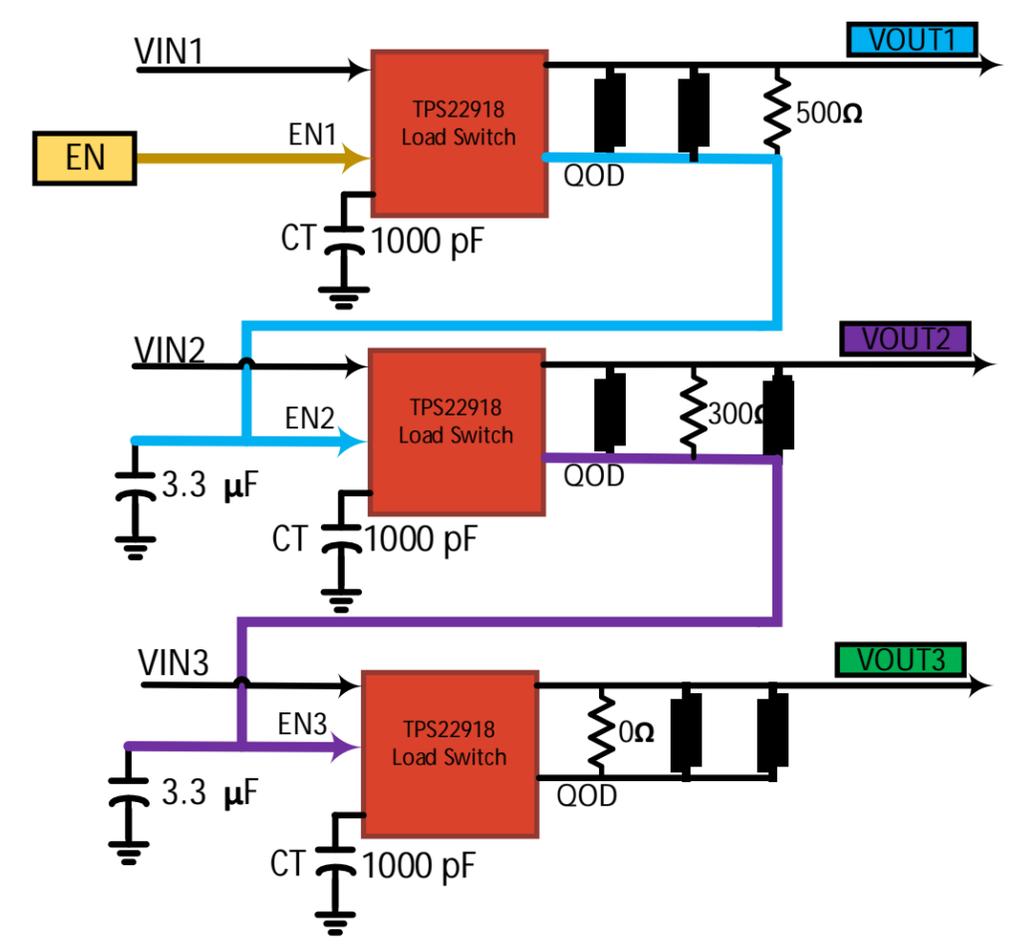
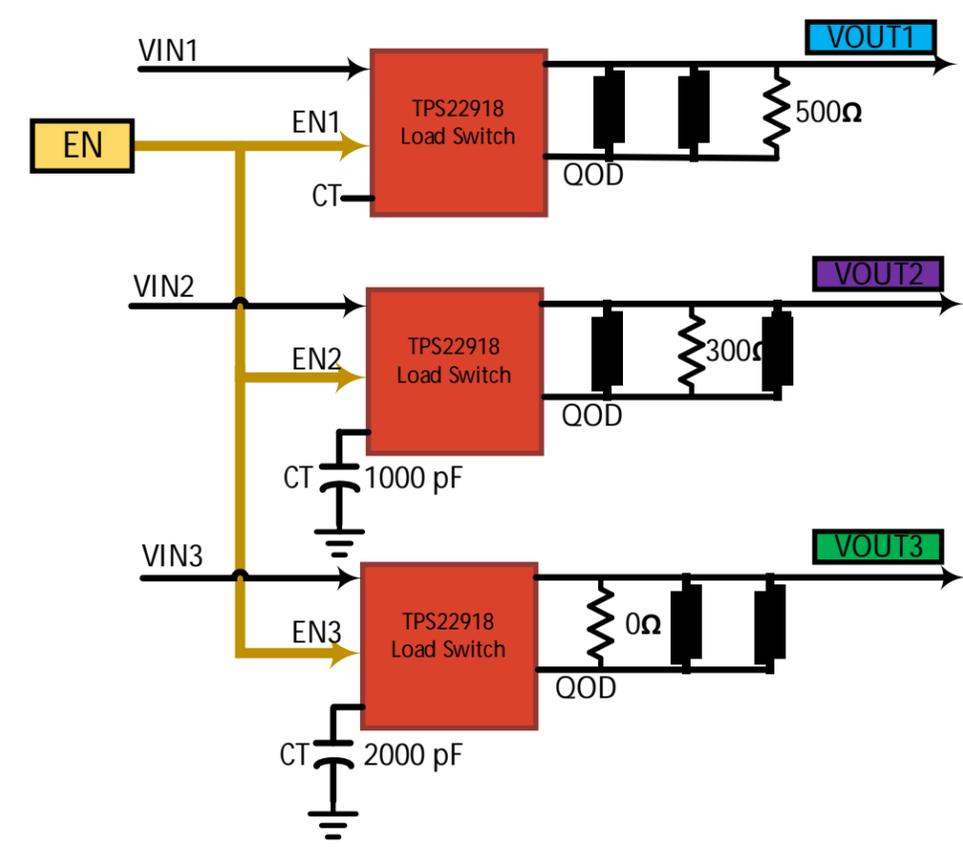
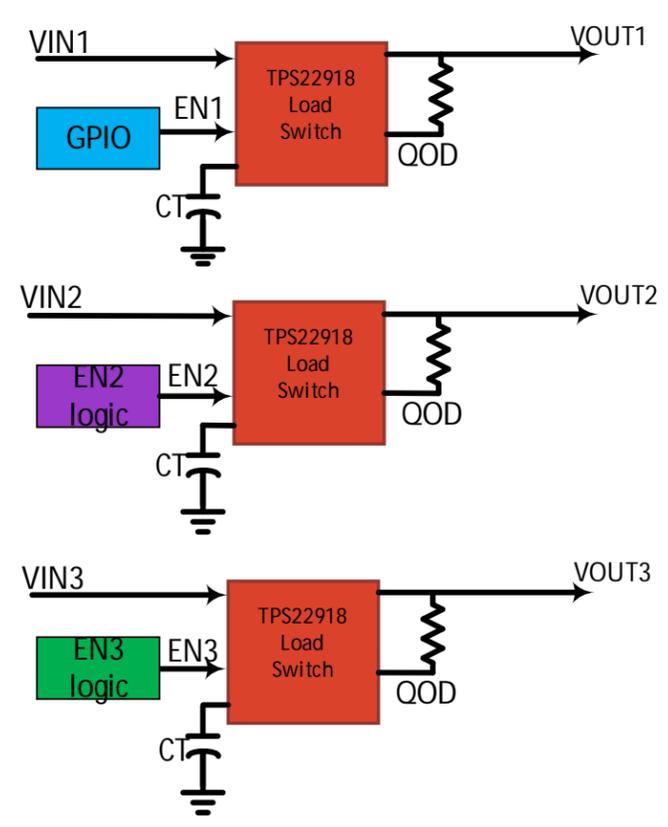


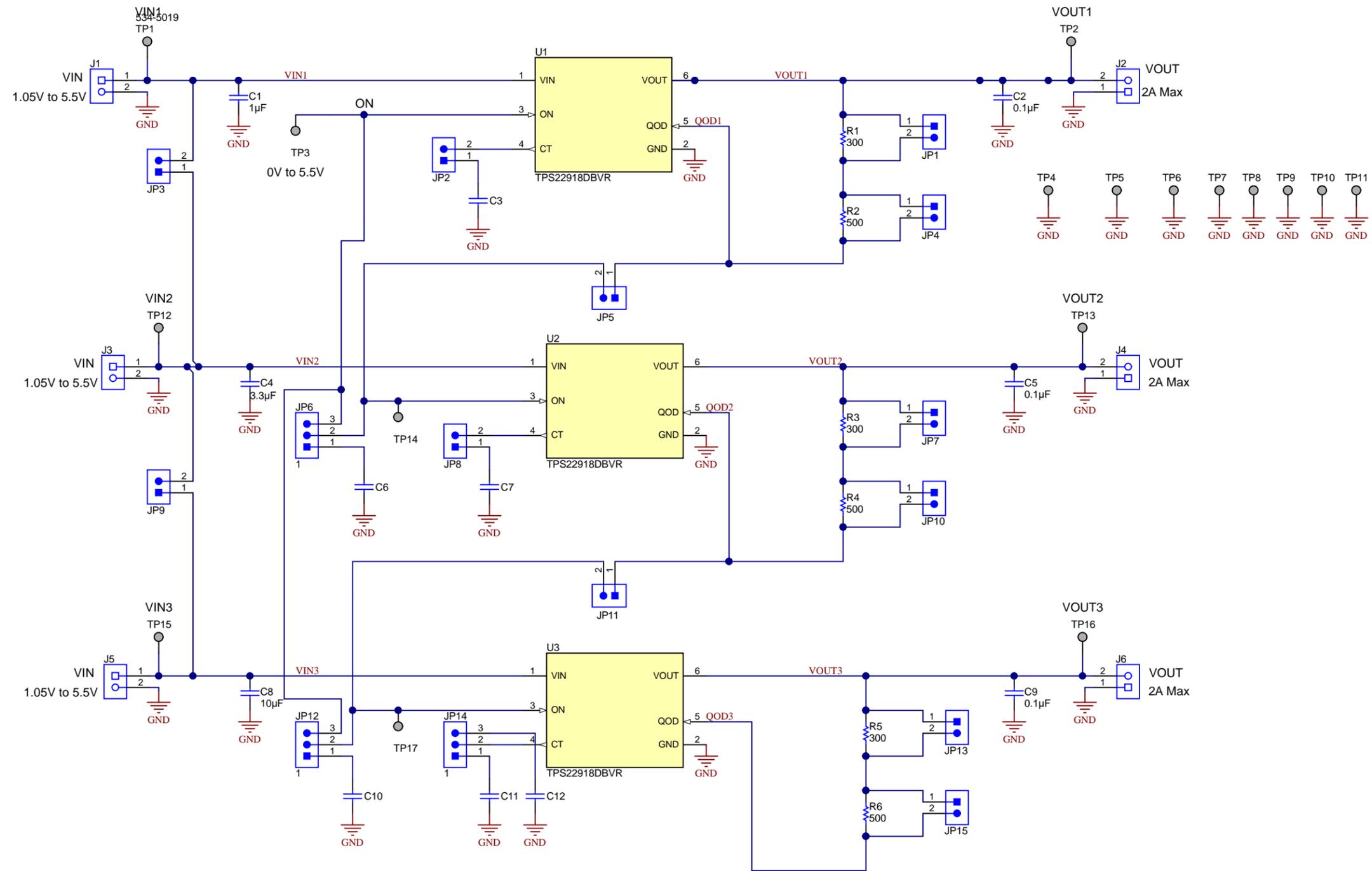
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 10/4/2017
TID #: N/A	Project Title: Power Sequencing TID	
Number: TIDA01584	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By:	File: Power_sequencing_CoverSheet.SchDoc	Size: B
Engineer: Arthur Huang	Contact: http://www.ti.com/support	http://www.ti.com





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Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 11/28/2017
TID #: N/A	Project Title: Power Sequencing TID	
Number: TIDA01584	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: Power_sequencing_BlankSheet.SchDoc	Size: B
Engineer: Arthur Huang	Contact: http://www.ti.com/support	



H1 SJ-5303 (CLEAR) H2 SJ-5303 (CLEAR) H3 SJ-5303 (CLEAR) H4 SJ-5303 (CLEAR)

DNP FID1 DNP FID2 DNP FID3

PCB Number: TIDA01584
PCB Rev: A

PCB LOGO PCB LOGO PCB LOGO

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 10/4/2017	 http://www.ti.com © Texas Instruments 2017
TID #: N/A	Project Title: Power Sequencing TID		
Number: TIDA01584	Rev: A	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By:	File: Power_sequencing_EVM_Hardware.SchDoc	Size: B	
Engineer: Arthur Huang	Contact: http://www.ti.com/support		

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